

ABSTRACT

A method for manufacturing an adhesive substrate with a die-cavity sidewall is disclosed. A region for forming die-cavity sidewall is defined on one surface of the substrate. The substrate is laminated with a sacrificial film, a partially cured resin is formed between the substrate and the sacrificial film. And then, an aperture is routed through the substrate, the partially cured resin, and the sacrificial film. The aperture is located corresponding to the region so that the substrate has a die-cavity sidewall formed inside the aperture. Thereafter, the sacrificial film is removed to expose the partially cured resin on the substrate so that the substrate with a die-cavity sidewall can have good adhesion.

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